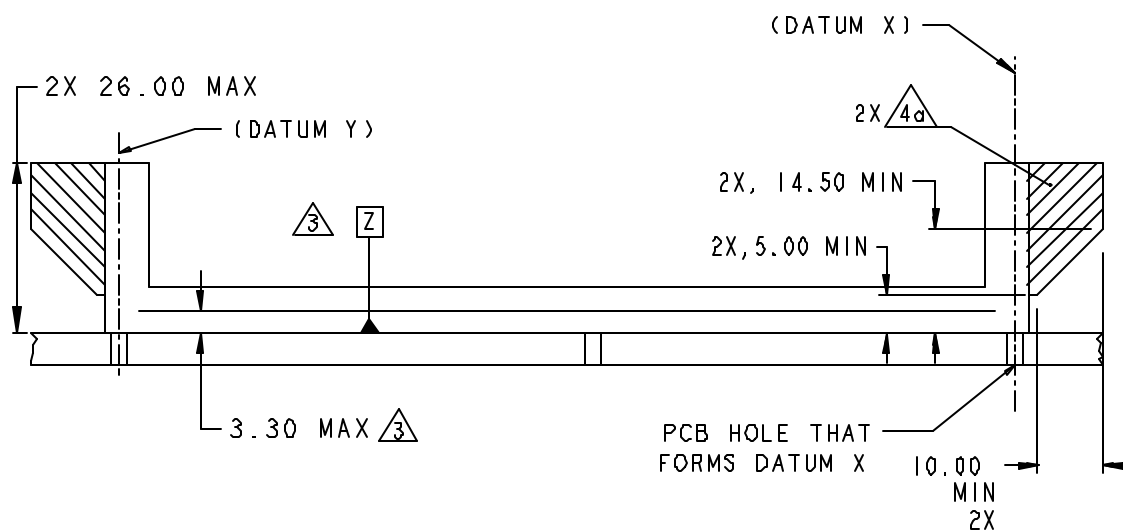
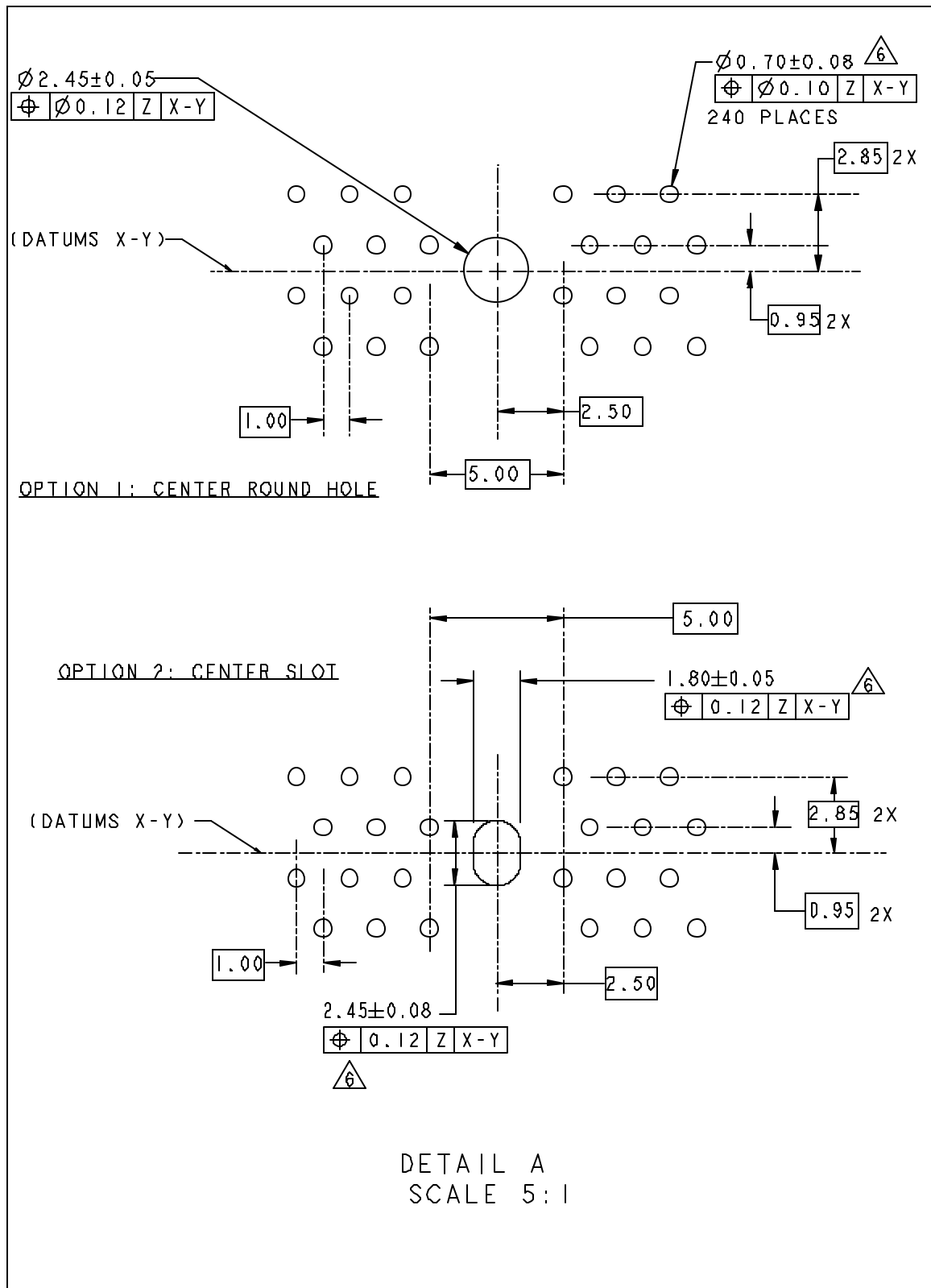


TOP VIEW (PCB FOOTPRINT ONLY)



SIDE VIEW (PCB AND SOCKET)

JEDEC SOLID STATE PRODUCT OUTLINE	THIS REGISTERED OUTLINE HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY, CHANGES ARE LIKELY TO OCCUR.					
TITLE 240 PIN DDRII SDRAM, 1.00mm CONTACT CENTERS, SOCKET OUTLINE	TITLE	DESIGNATOR	ISSUE B	DATE JULY 2003	SO-001	SHEET 1 OF 3




JEDEC SOLID STATE PRODUCT OUTLINE	TITLE 240 PIN DDRII SDRAM, 1.00mm CONTACT CENTERS, SOCKET OUTLINE	ISSUE B	DATE JULY 2003	SHEET SO-001 2 OF 3
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NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.


2. ALL DIMENSIONS ARE IN mm

 DIMENSION IS FROM TOP OF PCB (DATUM Z) TO THE SEATING PLANE OF THE DIMM IN THE SOCKET.

 KEEP OUT CROSS HATCHED AREA RESERVED FOR SOCKET EJECTORS BOTH ENDS.

 KEEP OUT ZONE IS HEIGHT LIMITED AS PER 

5. REFER TO 240 PIN DIMM REGISTERED OUTLINE MO-237 FOR MODULE DIMENSIONS.

 RECOMMENDED DIMENSIONS OF THESE FEATURES WERE DERIVED TO ALLOW A ROUTING SOLUTION ON THE MOTHERBOARD.

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE 240 PIN DDRII SDRAM, 1.00mm CONTACT CENTERS, SOCKET OUTLINE	ISSUE B	DATE JULY 2003	SO-001	SHEET 3 OF 3
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